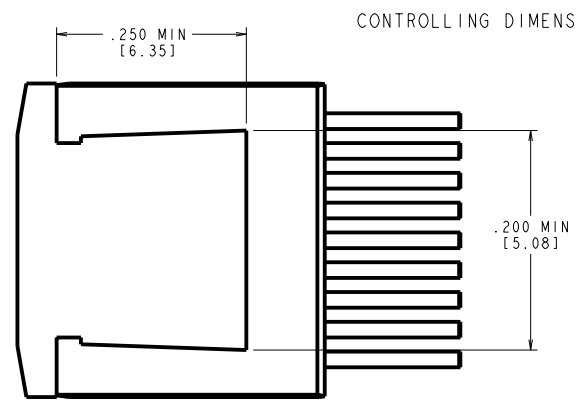
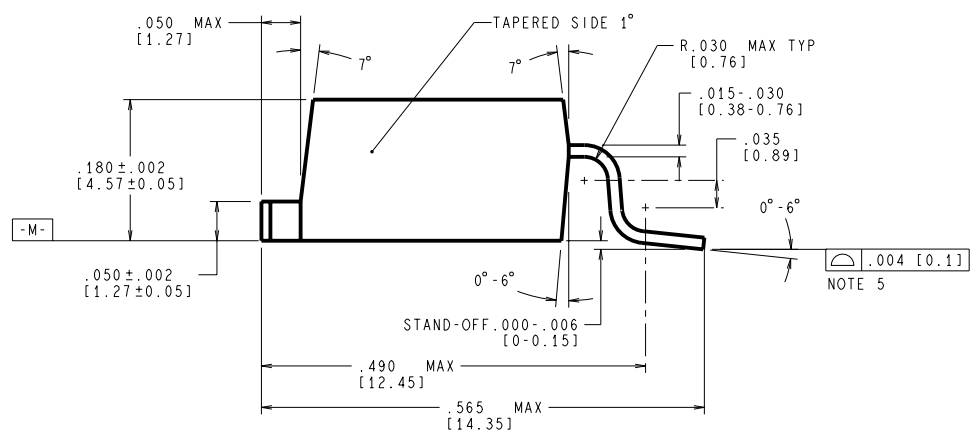
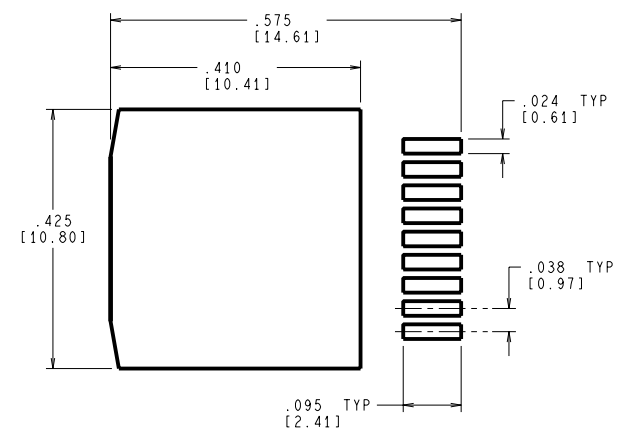
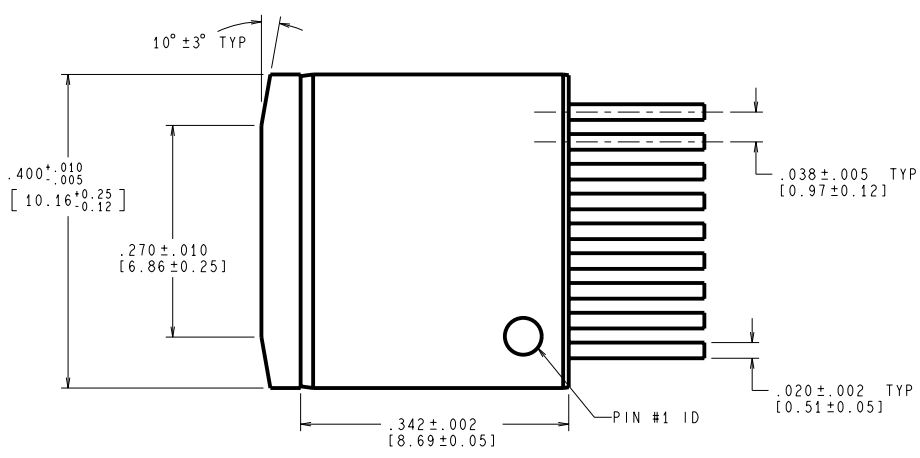


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10590	09/06/94	TL/



CONTROLLING DIMENSION: INCH

LEAD POSITION OVERLAY

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
200 MICROINCHES / 5.08 MICROMETERS MINIMUM LEAD/TIN
15/85 ON OLIN 194 COPPER OR EQUIVALENT.
- MAXIMUM VERTICAL BURR ON HEATSINK NOT TO EXCEED
.003 IN/ 0.05 mm.
- NO PACKAGE CHIPS, CRACKS OR SURFACE INDENTATION ALLOWED
AFTER FORMING.
- UNDER ALL CONDITIONS, LEAD(S) MUST NOT BE ABOVE DATUM -M-
AND NO LEADS MAY BE LOWER THAN .006 IN/ 0.15 mm MEASURED FROM
DATUM -M- TO THE BOTTOM OF THE LEADS.
- NO JEDEC REGISTRATION AS OF 09/06/1994.

APPROVALS		DATE		 2900 Semiconductor dr. Santa Clara, CA 95052-8090	
DRAWN: T. LEQUANG		09/06/94			
DFTG. CHK.					
ENGR. CHK.					
APPROVAL				TO-263, MOLDED, 9 LEAD, SURFACE MOUNT	
 PROJECTION INCH [MM]		SCALE N/A	SIZE C	DRAWING NUMBER MKT-TS9A	REV A
DO NOT SCALE DRAWING				SHEET 1 of 1	

SCALE: 7X